



Material Content Data Sheet



Sales Product Name	TLE9250LE			Issued	1. August 2018			
MA#	MA001675864							
Package	PG-TSON-8-1			Weight*	26.86 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.790	2.94	2.94	29396	29396
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		110	
	non noble metal	zinc	7440-66-6	0.012	0.04		439	
	non noble metal	iron	7439-89-6	0.236	0.88		8788	
wire	non noble metal	copper	7440-50-8	9.586	35.68	36.61	356828	366165
	non noble metal	copper	7440-50-8	0.046	0.17	0.17	1730	1730
	encapsulation	organic material	carbon black	1333-86-4	0.031	0.11		1142
	plastics	epoxy resin	-	1.580	5.88		58819	
	inorganic material	silicondioxide	60676-86-0	13.730	51.12	57.11	511099	571060
leadfinish	non noble metal	tin	7440-31-5	0.382	1.42	1.42	14227	14227
plating	noble metal	silver	7440-22-4	0.043	0.16	0.16	1618	1618
glue	plastics	epoxy resin	-	0.106	0.40		3951	
	noble metal	silver	7440-22-4	0.318	1.19	1.59	11853	15804
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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